## MMBTA92L, SMMBTA92L, MMBTA93L

## High Voltage Transistors PNP Silicon

### Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

Rating	Symbol	92	93	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	-300	-200	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-300	-200	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	-5.0	-5.0	Vdc
Collector Current — Continuous	Ι <sub>C</sub>	-500		mAdc

### **DEVICE MARKING**

MMBTA92L, SMMBTA92L = 2D; MMBTA93LT1 = 2E

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation FR–5 Board (Note 1) $T_A = 25^{\circ}C$	PD	225	mW
Derate above 25°C		1.8	mW/°C
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation (Note 2) Alumina Substrate, <sup>(2)</sup> $T_A = 25^{\circ}C$	PD	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction to Ambient	$R_{\thetaJA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

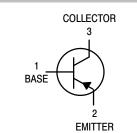
1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.

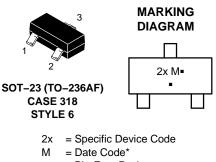
2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



### **ON Semiconductor®**

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= Pb–Free Package

(\*Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBTA92LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SMMBTA92LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
MMBTA92LT3G	SOT-23 (Pb-Free)	10000 / Tape & Reel
SMMBTA92LT3G	SOT-23 (Pb-Free)	10000 / Tape & Reel
MMBTA93LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please

refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### MMBTA92L, SMMBTA92L, MMBTA93L

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic			Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage (Note 3) ( $I_C = -1.0$ mAdc, $I_B = 0$ )	MMBTA92, SMMBTA92 MMBTA93	V <sub>(BR)CEO</sub>	-300 -200		Vdc
Collector-Base Breakdown Voltage ( $I_C = -100 \ \mu Adc, I_E = 0$ )	MMBTA92, SMMBTA92 MMBTA93	V <sub>(BR)CBO</sub>	-300 -200		Vdc
Emitter-Base Breakdown Voltage $(I_E = -100 \ \mu Adc, I_C = 0)$		V <sub>(BR)EBO</sub>	-5.0	-	Vdc
Collector Cutoff Current $(V_{CB} = -200 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -160 \text{ Vdc}, I_E = 0)$	MMBTA92, SMMBTA92 MMBTA93	I <sub>CBO</sub>	-	-0.25 -0.25	μAdo
Emitter Cutoff Current ( $V_{EB} = -3.0 \text{ Vdc}, I_C = 0$ )		I <sub>EBO</sub>	-	-0.1	μAdo
ON CHARACTERISTICS (Note 3)					
DC Current Gain ( $I_C = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$ ) ( $I_C = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$ ) ( $I_C = -30 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$ )	Both Types Both Types MMBTA92, SMMBTA92 MMBTA93	h <sub>FE</sub>	25 40 25 25	- - -	_
Collector – Emitter Saturation Voltage ( $I_C = -20$ mAdc, $I_B = -2.0$ mAdc)	MMBTA92, SMMBTA92 MMBTA93	V <sub>CE(sat)</sub>	-	-0.5 -0.5	Vdc
Base–Emitter Saturation Voltage $(I_C = -20 \text{ mAdc}, I_B = -2.0 \text{ mAdc})$		V <sub>BE(sat)</sub>	-	-0.9	Vdc
SMALL-SIGNAL CHARACTERISTICS				•	•
Current-Gain — Bandwidth Product		f⊤	50	_	MHz

Current-Gain — Bandwidth Product ( $I_C = -10$ mAdc, $V_{CE} = -20$ Vdc, f = 100 MHz)		f <sub>T</sub>	50	-	MHz
Collector–Base Capacitance ( $V_{CB} = -20$ Vdc, $I_E = 0$ , f = 1.0 MHz)	MMBTA92, SMMBTA92 MMBTA93		-	6.0 8.0	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.

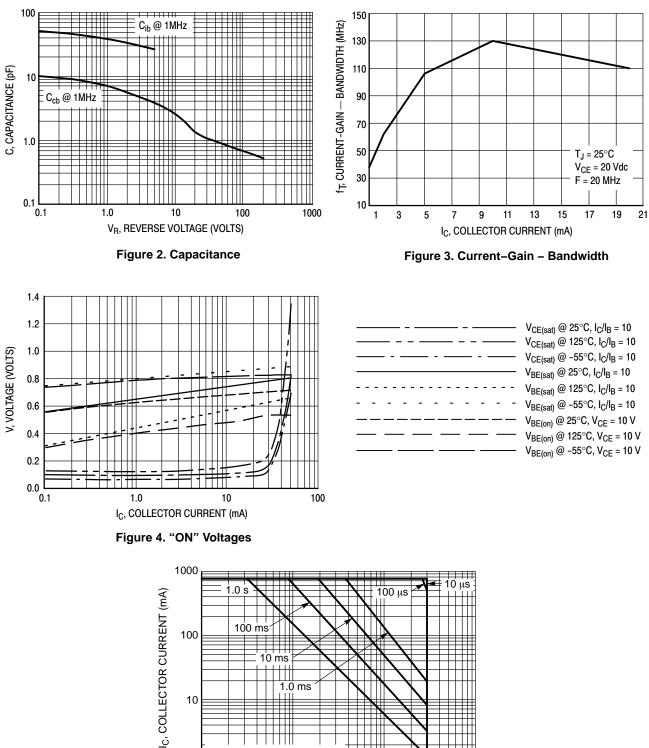
300  $V_{CE} = 10 \text{ Vdc}$  $T_J = +125^{\circ}C$ 250 hFE, DC CURRENT GAIN 200 25°C 150 -55°C 100 50 0 1.0 0.1 10

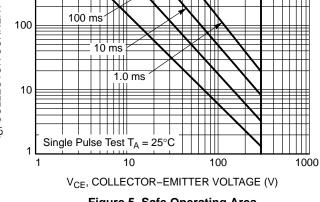
I<sub>C</sub>, COLLECTOR CURRENT (mA)

100

Figure 1. DC Current Gain

### MMBTA92L, SMMBTA92L, MMBTA93L





### MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

D

3

TOP VIEW

SIDE VIEW

Нe

DETAIL A

-3X b

## onsemi



SCALE 4:1

A\_\_\_\_ ' A1SOT-23 (TO-236) CASE 318 ISSUE AT

0.25

-L1

DETAIL A

END VIEW

DATE 01 MAR 2023

NDTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	IETERS			INCHES	
DIM	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
с	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10*	0*		10*



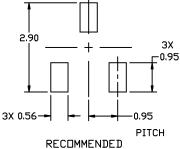


XXX = Specific Device Code

M = Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



MOUNTING FOOTPRINT

\* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

### **STYLES ON PAGE 2**

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### MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

# onsemi

### SOT-23 (TO-236) CASE 318 ISSUE AT

### DATE 01 MAR 2023

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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